Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK2965

# Switching Regulator, DC-DC Converter and Motor Drive Applications

• Low drain-source ON resistance :  $RDS (ON) = 0.15 \Omega (typ.)$ • High forward transfer admittance :  $|Y_{fs}| = 10 S (typ.)$ 

• Low leakage current :  $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 200 \text{ V)}$ 

• Enhancement-mode :  $V_{th} = 1.5 \sim 3.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$ 

### **Maximum Ratings (Ta = 25°C)**

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	200	V	
Drain-gate voltage (Ro	<sub>GS</sub> = 20 kΩ)	$V_{DGR}$	200	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	11	Α	
	Pulse (Note 1)	$I_{DP}$	33	Α	
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	35	W	
Single pulse avalanche	e energy (Note 2)	E <sub>AS</sub>	115	mJ	
Avalanche current		I <sub>AR</sub>	11	Α	
Repetitive avalanche e	energy (Note 3)	E <sub>AR</sub>	3.5	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	

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Weight: 1.9 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	3.57	°C / W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	62.5	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 50 V,  $T_{ch}$  = 25°C (initial), L = 1.53 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 11 A

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.

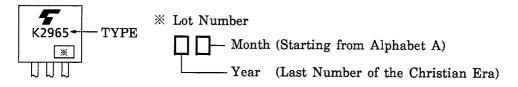
# **Electrical Characteristics (Ta = 25°C)**

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off cur	rent	I <sub>DSS</sub>	V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source bro	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	200	_	_	V
Gate threshold v	roltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5	_	3.5	V
Drain-source Of	N resistance	R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 5.5 A	_	0.15	0.26	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 5.5 A	5.0	10	_	S
Input capacitano	е	C <sub>iss</sub>		_	1200	_	
Reverse transfer	capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	100	_	pF
Output capacitance		Coss	1	_	290	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} = 100V$ $V_{GS} = 100V$ $V_{OUT} = 100V$ $V_{OUT} = 100V$	_	15	_	- ns
	Turn-on time	t <sub>on</sub>		_	25	_	
	Fall time	t <sub>f</sub>		_	10	1	
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm w} = 10\mu \rm s$	_	75	_	
Total gate charge (gate–source plus gate–drain)		Qg		_	30	1	_
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 100 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$		20	_	nC
Gate-drain ("miller") Charge		$Q_{gd}$			10	_	

# **Source-Drain Ratings and Characteristics (Ta = 25°C)**

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	11	А
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	33	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 11 A, V <sub>GS</sub> = 0 V	_	_	-2.0	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 11 A, V <sub>GS</sub> = 0 V, I <sub>DR</sub> / dt = 100 A / μs	_	175	-	ns
Reverse recovery charge	Q <sub>rr</sub>		_	1.3	_	μC

## Marking



2 2002-09-02

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